



Material Composition Declaration

EPC2071

Company Name	Efficient Power Conversion (EPC)	Issue Date:	5/16/2022
Contact Name:	Yanping Ma	Contact Title:	VP Quality
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Part Weight:	14.1 mg	Type of Product:	eGaN FET

Construction Element	Substance	CAS No. If Applicable	Weight	Mass	Sum	Mass
			(mg)	(%)	(%)	(ppm)
Chip	Silicon	7440-21-3	11.8059	83.7002	87.4297	837002
	Silicon oxide	7631-86-9	0.0786	0.5572		5572
	Silicon nitride	12033-89-5	0.0244	0.1727		1727
	Gallium nitride	25617-97-4	0.0588	0.4168		4168
	Aluminum	7429-90-5	0.1168	0.8281		8281
	Aluminum nitride	24304-00-5	0.0125	0.0885		885
	Titanium	7440-32-6	0.0024	0.0171		171
	Titanium nitride	25583-20-4	0.1120	0.7943		7943
	Copper	7440-50-8	0.0019	0.0138		138
	Tungsten	7440-33-7	0.0110	0.0783		783
	Polyimide		0.1076	0.7626	7626	
Under Bump Metal	Titanium	7440-32-6	0.0013	0.0095	0.1041	95
	Copper	7440-50-8	0.0133	0.0946		946
Solder Bump	Copper	7440-50-8	0.1335	0.9462	12.4662	9462
	Nickel	7440-02-0	0.0796	0.5644		5644
	Tin	7440-31-5	1.5175	10.7583		107583
	Silver	7440-22-4	0.0278	0.1972		1972
Sum in total:			14.1050	100.0000	100.0000	1000000

Note:

The substance content disclosed herewith is approximate and is based on engineering calculation. Statements are based on our present knowledge and may subject to change at any time due to technical requirements and development. EPC may update this document without notification. Statement may not include information regarding the minute quantities of dopant and metal materials in the electrical devices contained within the finished product.